IN THE CLAIMS

Please amend the claims as follows:

Claims 1-7 (Cancelled).

Claim 8 (Currently Amended): A high-pressure processing apparatus for processing an object by high pressure fluid, comprising:

a processing vessel including a processing chamber in which the object may be processed ~~formed therein~~;

a support member which supports [[an]] the object ~~loaded~~ in the processing chamber ~~thereon~~;

fluid feeding/discharging means which feeds and discharges a high-pressure fluid in and out of the processing chamber;

a communicating channel provided in addition to the fluid feeding/discharging means, wherein said communicating channel ~~which~~ is formed in the processing vessel to communicate with the processing chamber;

a first valve ~~structural~~ member which is operatively supported to the processing vessel ~~in the communicating channel~~ to open and ~~openably~~ close the communicating channel; and

a pipe ~~piping~~ member which is communicated and connected to the communicating channel for feeding and/or discharging a ~~corrosive fluid~~ chemical in and out of the processing chamber~~, the corrosive fluid being different from the high-pressure fluid~~ for processing the object.

Claim 9 (Currently Amended): The apparatus according to claim 8, wherein the pipe ~~piping~~ member is so constructed as to be usable under an atmospheric pressure.

Claim10 (Currently Amended): The apparatus according to claim 8, wherein the fluid ~~feeding~~ feeding/discharging means includes a fluid feeding channel which is formed in the processing vessel to communicate with the processing chamber, a second valve ~~structural~~ member which is operatively supported [[to]] at the processing vessel ~~in the fluid feeding channel~~ to ~~openably~~ open and close the fluid feeding channel, and a ~~piping~~ pipe member which is communicated and connected to the fluid feeding channel to feed and/or discharge the high-pressure fluid in and out of the processing vessel.

Claim 11 (Currently Amended): The apparatus according to claim 8, further comprising a fluid feeding hole ~~which is~~ formed in the first valve ~~structural~~ member through which ~~to feed~~ the high-pressure fluid is fed into the processing chamber.

Claim 12 (Currently Amended): The apparatus according to claim 8, wherein the processing chamber includes a reservoir section which temporarily stores the chemical ~~a corrosive fluid~~ therein before the chemical is fed ~~to feed the corrosive fluid~~ onto the object, wherein the fluid ~~feeding~~ feeding/discharging means is so constructed as to feed the high-pressure fluid into the reservoir section.

Claim 13 (Withdrawn): A high-pressure processing method comprising the steps of:

feeding a corrosive fluid into a processing chamber of a pressure vessel;

washing an object supportively loaded in the processing chamber with the corrosive fluid under an atmospheric pressure;

discharging the corrosive fluid out of the processing chamber; and

feeding a high-pressure fluid into the processing chamber to dry the object.

Claim 14 (Withdrawn): A high-pressure processing method comprising the steps of:

feeding a corrosive fluid into a processing chamber of a pressure vessel;

applying a developer onto an object supportively loaded in the processing chamber under an atmospheric pressure for development;

discharging the corrosive fluid out of the processing chamber; and

feeding a high-pressure fluid into the processing chamber to wash and dry the object.

Claim 15 (New): The apparatus according to claim 12, wherein the reservoir section has a shower head structure.

Claim 16 (New): The apparatus according to claim 8, wherein the support member is rotatable about an axis of rotation in the processing vessel, and the communicating channel is arranged to be coaxial with the support member.

Claim 17 (New): The apparatus according to claim 8, wherein the pipe member includes a plurality of branch pipe members through which different kinds of chemicals are supplied to the communicating channel.

Claim 18 (New): The apparatus according to claim 8, wherein the object is a semiconductor wafer and the high pressure fluid is supercritical fluid or subcritical fluid.

Claim 19 (New): The apparatus according to claim 8, wherein the fluid feeding/discharging means feeds and discharges high pressure fluid in and out of the processing chamber to dry the object.

Claim 20 (New): The apparatus according to claim 8, wherein the first valve member includes a poppet valve and the chemical is fed through the communicating channel into the processing chamber via the first valve in an open state.